

### **AMENDMENTS TO THE SPECIFICATION**

**Kindly amend paragraph [0116] spanning pages 71 and 72 as follows:**

In Figs. 5(a) to 5(c), the major steps of the first method for producing a wiring transfer sheet of the present invention are shown. In Fig. 5(a), a carrier base 501 and a wiring material sheet 502 are shown, respectively. In Fig. 5(d), an enlarged view of Area A of a surface of wiring material sheet. As shown in Fig. 5(d), on the entire surface of the wiring material sheet, bump-shaped, mushroom-shaped, or bud-shaped ~~concavities~~convexities 530 are formed. The junction layer (not shown) may be previously formed on the surface of the carrier base 501 or the wiring material sheet 502. Further, the surface of the carrier base 501 may be previously subjected to a releasing treatment.